

IEEE 802.3 400 Gb/s/Lane Signaling Study Group meeting

September 2026 Interim Hybrid Meeting

Lisbon, Portugal, Western European Summer Time (WEST)

Meeting Minutes, Prepared by Beth Kochuparambil

Day 1 – Sept 15, 2026

Kent Lusted as IEEE 802.3 400 Gb/s/lane Study Group Chair called the meeting to order at 1:20 pm (WEST)

Presentation #1 Agenda and General Information

Presenter: Kent Lusted

https://www.ieee802.org/3/400GPL/public/2609/agenda_400GPL_2609.pdf

The Chair reminded participants to declare their affiliation in the online meeting tool. Failure to do so would result in expulsion from the meeting. He also reminded participants that registration is required for this meeting.

The Chair asked if there were any modifications to the agenda (see slide #4). There were no modifications requested. There were no objections. Agenda approved.

The Chair pointed to the minutes from a recent Study Group Telephonic Interim (see slide #5) stating that he, nor Beth Kochuparambil, received feedback on the minutes, and none brought up on the floor. The Chair asked if there was opposition to approving the minutes. No one objected. Minutes approved

The Chair reminded participants to follow the meeting decorum rules. The Chair asked for members of the press to identify themselves. No one identified as such.

The Chair presented the second slide of the IEEE SA Pre-PAR Patent Policy slides (see slide #26).

The Chair presented the second slide of the IEEE SA Copyright Policy slides (see slide #28).

The Chair reminded participants of the IEEE Code of Ethics and Conduct (see slide #30). He noted “All participants in IEEE-SA activities are expected to adhere to the core principles underlying the IEEE Code of Ethics and IEEE Code of Conduct”.

The Chair presented the second slide (see slide #31) of the IEEE SA Participation Policy slides. The Chair noted – “Participants in the IEEE-SA “individual process” shall act independently of

others, including employers. By participating in standards activities using the “individual process”, you are deemed to accept these requirements; if you are unable to satisfy these requirements then you shall immediately cease any participation.”

The Chair presented the third slide (see slide #32) of the IEEE SA Participation Policy. Chair noted that IEEE-SA standards activities should allow the fair & equitable consideration of all viewpoints, and The IEEE-SA Standards Board Bylaws (clause 5.2.1.3) specifies that “the standards development process shall not be dominated by any single interest category, individual, or organization”.

The Chair noted the IEEE Ethics Reporting Line (see slide #34) to the participants.

The Chair asked if any clarification was needed on IEEE SA Policies. There was none.

The Chair expressed the goals for the meeting (see slide #13) and ground rules.

The Chair stated that attendance will be taken via IMAT and noted that it counted towards IEEE 802.3 Working Group voting membership and provided the link to mark one’s attendance.

The Chair gave eligible individuals time to fill out IMAT for attendance. No one indicated needing more time.

1:32 pm – The meeting Chair responsibilities was handed over to Mark Nowell, IEEE 802.3 400 Gb/s/lane Study Group Vice-Chair.

Presentation #2 Nomenclature for 400GPL

Presenter: Kent Lusted

https://www.ieee802.org/3/400GPL/public/2609/lusted_400GPL_01_2609.pdf

Clarifying questions on the presentation occurred.

1:46 pm – The meeting Chair responsibilities was handed back to Kent Lusted as Chair.

Presentation #3 400G/800G/1.6T Logic Architecture

Presenter: Gary Nicholl

https://www.ieee802.org/3/400GPL/public/2609/nicholl_400GPL_01_2609.pdf

Clarifying questions and discussion on the presentation occurred.

Presentation #4 Extended link training protocol

Presenter: Leon Bruckman

https://www.ieee802.org/3/400GPL/public/2609/bruckman_400GPL_01_2609.pdf

Clarifying questions and discussion on the presentation occurred.

Break at 2:53 pm. Meeting resumed at 3:30 pm.

Presentation #5 Maintenance channel for 400GPL

Presenter: Adee Ran

https://www.ieee802.org/3/400GPL/public/2609/ran_400GPL_01_2609.pdf

Clarifying questions and discussion on the presentation occurred.

The Chair gave eligible individuals time to fill out IMAT for attendance. No one indicated needing more time. (4:32p.m.)

The Chair received 2 straw poll requests, plus ran a trial straw poll as this was the first straw poll with slido for the session..

Straw Poll #1

No Question - Run for testing

Straw Poll #2

I would support the starting assumptions for the logic architecture as summarized in slide 9 of nicholl_400GPL_01_2609?

Yes / No / Need More Information

Results: Y: 72 N: 0 NMI: 10

Straw Poll #3

For the PHY types we are defining in this project, I believe we should include AUIs with these rates:

- A) 400G/lane
- B) 400G/lane, 200G/lane
- C) 400G/lane, 200G/lane and 100G/lane

D) 400G/lane, 200G/lane, 100G/lane and 50G/lane*
*NOTE: 50G/lane option only applies for 400GbE

Results: A: 4 B: 51 C: 32 D: 4

The Chair invited David Rogers from the Ethernet Alliance (meeting host) to give details on the social.

Break for the day at 5:19 pm.

Day 2 – Sept 16, 2026

Meeting resumed at 8:45 am.

The Chair welcomed participants and displayed Presentation #1 again (https://www.ieee802.org/3/400GPL/public/2609/agenda_400GPL_2609.pdf). He made a few announcements:

- Session reminders (see slide #2)
- Outlined the plan for the day (see slide #7)
- Confirmed that IEEE policies (see slide #12) were known and understood
- Updates were posted to Welch, Xu, Mellitz presentation

Presentation #6 Scaling the Rack: Electrical Interconnect for Hyperscaler Compute Demands

Presenter: Halil Cirit

https://www.ieee802.org/3/400GPL/public/2609/cirit_400GPL_01a_2609.pdf

Clarifying questions and discussion on the presentation occurred.

The Chair reminded eligible participants to sign into IMAT to mark their attendance.

Break at 9:59 am. Meeting resumed at 10:26 pm.

Presentation #7 Pre-Baseline Discussion for 400GPL Single Wavelength Objectives

Presenter: Brian Welch

https://www.ieee802.org/3/400GPL/public/2609/welch_400GPL_01a_2609.pdf

Clarifying questions and discussion on the presentation occurred.

The Chair gave eligible individuals time to fill out IMAT for attendance. No one indicated needing more time. (11:58 am)

The Chair reminded participants that recording the meeting of any kind is prohibited, this includes photos, AI, or transcription within the online tool or local on ones computer. (see Presentation #1, slide #9)

The Chair made announcements regarding logistics.

Presentation #8 Further consideration on modulation formats of 400Gbps per lane optical signal

Presenter: Yu Xu

https://www.ieee802.org/3/400GPL/public/2609/xu_y_400GPL_01a_2609.pdf

Clarifying questions and discussion on the presentation occurred.

Presentation #9 Chip to Module and Optics Objectives

Presenter: Ali Ghiasi

https://www.ieee802.org/3/400GPL/public/2609/ghiasi_400GPL_01a_2609.pdf

Clarifying questions and discussion on the presentation occurred.

The Chair reminded eligible participants to sign into IMAT for attendance.

Break at 12:11 pm. Meeting resumed at 1:18 pm.

Presentation #10 Continuing discussion on interfaces necessary for NPO architecture in EEE802.3dv

Presenter: Guangcan Mi

https://www.ieee802.org/3/400GPL/public/2609/mi_g_400GPL_01_2609.pdf

Clarifying questions and discussion on the presentation occurred.

Presentation #11 A Salz-Inspired Implementation Margin Estimate Aiding 400 Gb/s/Lane Channel Objective and Baseline Refinement

Presenter: Rich Mellitz

https://www.ieee802.org/3/400GPL/public/2609/mellitz_400GPL_01_2609.pdf

Clarifying questions and discussion on the presentation occurred.

2:45 pm - The Chair reminded eligible participants to sign into IMAT for attendance.

Presentation #12 Package Considerations for 400GPL BGA-Side Feasibility Studies

Presenter: Toshiaki Sakai

https://www.ieee802.org/3/400GPL/public/2609/sakai_400GPL_01_2609.pdf

Clarifying questions and discussion on the presentation occurred.

Break at 3:15 pm. Meeting resumed at 3:45 pm.

Presentation #13 Industry Need for Higher Capacity MDI Connectors

Presenter: John D'Ambrosia

https://www.ieee802.org/3/400GPL/public/2609/dambrosia_400GPL_01_2609.pdf

The presenter clarified that the content of the presentation shifted after he made his request, however didn't change the title for ease of logistics. Clarifying questions and discussion on the presentation occurred.

Presentation #14 Considering a KR Objective

Presenter: Nathan Tracy

https://www.ieee802.org/3/400GPL/public/2609/tracy_400GPL_01c_2609.pdf

Clarifying questions and discussion on the presentation occurred.

Straw Poll #4

I support the addition of a KR objective to the P802.3dv project.

Yes / No / Need more information

Results: Y: 83 N: 2 NMI: 8

The Chair reminded eligible participants to sign into IMAT, see their email for social details, and Thursday is a 9am start time.

Presentation #15 Inclusion of CPO channels in the 400G/lane Optical Specifications

Presenter: Vishnu Balan

https://www.ieee802.org/3/400GPL/public/2609/balan_400GPL_01b_2609.pdf

Clarifying questions and discussion on the presentation occurred.

Break for the day at 6:01 pm.

Day 3 – Sept 17, 2026

Meeting resumed at 9:04 am.

The Chair welcomed participants and displayed Presentation #1 again

(https://www.ieee802.org/3/400GPL/public/2609/agenda_400GPL_2609.pdf). He made a few announcements:

- Session reminders (see slide #2)
- Confirmed that IEEE policies (see slide #12) were known and understood
- Reminded participants of the AI use policy
- Reminded eligible participants to sign into IMAT
- Outlined the plan for the day (see slide #8). Drew attention to a presentation posted late, ran_02

Presentation #16 Path Forward for Developing IEEE 802.3 400GPL C2M/CR Specifications

Presenter: Mike Li

https://www.ieee802.org/3/400GPL/public/2609/li_m_400GPL_02_2609.pdf

Clarifying questions and discussion on the presentation occurred.

Presentation #17 Modulation wars: How to steer through uncertainty

Presenter: Adele Ran

https://www.ieee802.org/3/400GPL/public/2609/ran_400GPL_02a_2609.pdf

Clarifying questions and discussion on the presentation occurred.

Break at 10:51 am. Meeting resumed at 11:22 am.

The Chair reminded eligible participants to sign into IMAT for attendance.

Presentation #18 Architecture and Methodology Considerations for Developing IEEE 802.3 400GPL C2M/CR PAM4/PAM6 Specifications

Presenter: Mike Li

https://www.ieee802.org/3/400GPL/public/2609/li_m_400GPL_01_2609.pdf

Clarifying questions and discussion on the presentation occurred.

Break at 12:21 pm. Meeting resumed at 1:23 pm.

The Chair reminded eligible participants to sign into IMAT for attendance.

Presentation #19 Modulation and FEC scheme for 400G/lane AUI-C2M

Presenter: Xiang He

https://www.ieee802.org/3/400GPL/public/2609/he_x_400GPL_01_2609.pdf

Clarifying questions and discussion on the presentation occurred.

Presentation #20 Modulation and FEC scheme for 400G/lane CR objectives

Presenter: Xiang He

https://www.ieee802.org/3/400GPL/public/2609/he_x_400GPL_02a_2609.pdf

Clarifying questions and discussion on the presentation occurred.

Straw Poll #5: (Optical Modulation)

I support PAM4 optical modulation as the basis to develop baselines against the optical objectives:

Yes / No / NMI

Results: Y: 82 N: 1 NMI: 3

Straw Poll #6: (Backplane Objective Language Form)

I prefer backplane objective language of the form:

- A. Define a single-lane physical layer specification that supports 400 Gb/s operation over electrical backplanes with insertion loss up to at least X dB at Nyquist frequency (of Y GHz)
- B. Define a single-lane physical layer specification that supports 400 Gb/s operation over electrical backplanes with insertion loss up to at least the insertion loss of a die-to-die channel supporting a 1 meter twin-axial copper cable

NOTE: This straw poll is on the general direction of the objective form.

Results: A: 22 B: 72

Break at 3:17 pm. Meeting resumed at 3:40 pm.

The Chair gave eligible individuals time to fill out IMAT for attendance. No one indicated needing more time. (3:41 pm)

Straw Poll #7: (Backplane Objective Language Form)

I prefer backplane objective language of the form:

- A. Define a single-lane physical layer specification that supports 400 Gb/s operation over electrical backplanes
- B. Define a single-lane physical layer specification that supports 400 Gb/s operation over electrical backplanes with insertion loss up to at least the insertion loss of a die-to-die channel supporting a 1 meter twin-axial copper cable

NOTE: This straw poll is on the general direction of the objective form.

Results: A: 32 B: 42

4:17 pm – The meeting chair responsibilities were handed over to Mark Nowell.

4:21 pm – The meeting chair responsibilities were handed back to Kent Lusted.

Motion #1: (Backplane Objective)

Move to adopt the following objectives:

- Define a single-lane physical layer specification that supports 400 Gb/s operation over electrical backplanes
- Define a two-lane physical layer specification that supports 800 Gb/s operation over electrical backplanes
- Define a four-lane physical layer specification that supports 1.6 Tb/s operation over electrical backplanes

M: J. D'Ambrosia

S: N. Swenson

Technical ($\geq 75\%$)

Results: Y: 74 N: 0 A: 6

Motion Passes at 4:29 pm

Straw Polls #8 & 9: Electrical Modulation (taken together)

I believe PAM6 electrical interfaces should be standardized in IEEE P802.3dv.

Y/N/NMI

I believe PAM4 electrical interfaces should be standardized in IEEE P802.3dv.

Y/N/NMI

Results:

SP8 (PAM6) – Y: 54 N: 17 NMI: 20

SP9 (PAM4) – Y: 85 N: 1 NMI: 6

The Chair lead a discussion with participants: What are your top interests of needed information to help form your opinion on modulation of 400GPL electrical interfaces (not ordered)

- Channel improvements needed for PAM4 vs PAM6
- Channel impairments effects on different modulations, including skew
- PMA adjustments for PAM6
- Spec considerations for PAM6
- Comprehensive comparison, including FEC
- Power comparison
- Spparameters of 1m cable assembly & backplane channels
- Hard decisions vs soft decisions for PAM6
- Reference Receiver
- Package details
- Proposed electrical MDI(s)

The Chair displayed slides 23-24 of Presentation #1

(https://www.ieee802.org/3/400GPL/public/2609/agenda_400GPL_2609.pdf).

Meeting adjourned at 5:06 pm.

Attendance (as recorded in IMAT)

Name (Last, First)	Affiliation	Employer	9/15	9/16	9/17
Akinwale, Oluwafemi	Intel Corporation	Intel Corporation	X	X	X
Alloin, Laurent	Ciena Corporation		X	X	X
Bao, Tina	Tyco		X	X	X
Ben-Artsi, Liav	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.		X	X
Benyamin, Saied	Ethernovia	Ethernovia			X
Bernier, Eric	Huawei Technologies Canada Co., Ltd.	Huawei Technologies Canada Co., Ltd.	X	X	X
Brooks, Paul	Viavi Solutions	Viavi solutions GmbH	X	X	X
Brown, Matthew	Qualcomm	Alphawave Semi	X	X	X
Bruckman, Leon	NVIDIA	NVIDIA	X	X	X
Calvin, John	Keysight Technologies	Keysight Technologies	X	X	X
Castro, Jose	Panduit Corp.	Panduit	X	X	X
Chen, Chan	Independent/AOI	Self Employed	X	X	X
chen, jinhua	Luxshare Tech; Luxshare-ICT	Luxshare-ICT	X	X	X
Chen, Lihao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X	X	X
Choudhury, Golam	Genuine Optics	Genuine Optics	X	X	X
Cole, Christopher R	Coherent Corp.	Coherent Corporation	X	X	
Cox, Ian	Broadcom Corporation		X	X	X
Cusmai, Marco	Synopsys, Inc.		X	X	X
D'Ambrosia, John	Futurewei Technologies, U.S. Subsidiary of Huawei	Futurewei Technologies, U.S. Subsidiary of Huawei	X	X	X

Dai, Shaoan	Infineon Technologies				X
Dar, Marva	TE Connectivity	TE Connectivity	X	X	X
Dawe, Piers J G	Nvidia	NVIDIA	X	X	X
de Koos, Andras	Microchip Technology Inc	Microchip Technology Inc	X	X	X
Dosunmu, Olufemi	Texas Instruments Inc.			X	
Dsilva, Hansel	Amphenol Corporation		X	X	X
Dudek, Michael	Marvell	Marvell	X	X	X
Dziedzic, Devin	The Siemon Company			X	X
El-Chayeb, Ahmad	Keysight Technologies Inc	Keysight Technologies Inc	X	X	X
Elattar, Mohamed	Huawei Technologies Duesseldorf GmbH				X
Engenhardt, Klaus	Teradyne, Inc. & Quantifi Photonics		X	X	X
Estrakh, Daniel	Valens Semiconductor	Valens Semiconductor		X	X
Ferretti, Vincent	Corning Incorporated	Corning Incorporated	X	X	
Galan, Jose	MaxLinear, Inc.	MaxLinear, Inc.	X	X	X
Gareau, Sebastien	Ciena Corporation		X	X	X
Gauthier, Claude	ForestSemi	ForestSemi	X	X	X
Geng, Limin	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X	X	X
Ghamsari, Behnood	Molex Incorporated			X	X
Ghiasi, Ali	Ghiasi Quantum LLC; Marvell Semiconductor, Inc.	Ghiasi Quantum LLC	X	X	X
Gilb, James	General Atomics Aeronautical Systems, Inc.	General Atomics Aeronautical Systems, Inc.		X	
Gorshe, Steven Scott	Microchip Technology, Inc.	Microchip Technology, Inc.			X
Hamilton, Mark	Cadence Design Systems	Cadence Design Systems	X	X	X

Han, Ruibo	China Mobile Communications Corporation (CMCC)	China Mobile Communications Corporation (CMCC)	X	X	X
He, Xiang	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X	X	X
Healey, Adam	Broadcom Inc.	Broadcom Inc.	X	X	X
Heck, Howard	TE Connectivity	TE Connectivity	X	X	X
Helely, Oren	Marvell Semiconductor, Inc.		X	X	X
Hiroaki, Kukita	Yamaichi Electronics	Yamaichi Electronics	X	X	X
Hon, Kam Yan	Cisco Systems, Inc.		X	X	
Hu, Runlong	China Mobile Communications Group Co.	China Mobile Communications Group Co.	X	X	X
Huang, Kechao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X	X	X
Huber, Thomas	Nokia	Nokia	X	X	X
Isono, Hideki	Furukawa FITEL Optical Components	Furukawa FITEL Optical Components Limited	X	X	X
Issenhuth, Tom	Huawei Technologies Co., Ltd	Issenhuth Consulting, LLC	X	X	X
Jackson, Kenneth	Sumitomo Electric Industries, LTD	Sumitomo Electric Industries, LTD	X	X	X
Johnson, John	Broadcom Corporation	Broadcom Corporation	X	X	X
Jones, Chad	Cisco Systems, Inc.	Cisco Systems, Inc.	X	X	
Kareti, Upen	Cisco Systems, Inc.	Cisco Systems, Inc.	X	X	X
KATO, TAKAHIRO	Dexerials	Dexerials	X	X	X
Kaygusuz, Ahmet	Adhoc Teknoloji A.Ş.	Adhoc Teknoloji	X	X	X
Kim, Andrew	Luxshare Tech	Spectra7 Microsystems	X	X	X
Kim, DoKyun	LG ELECTRONICS	LG ELECTRONICS			X
Kimber, Eric	Semtech Ltd	Semtech Ltd	X	X	X
Koch, Lavi	Lavi Koch Nvidia		X	X	

Kochuparambil, Elizabeth	Cisco Systems, Inc.	Cisco Systems, Inc.	X	X	X
Kocsis, Sam	Amphenol Corporation	Amphenol Corporation	X	X	X
Kondo, Taiji	Dexerials Corporation	Dexerials Corporation	X	X	X
Kutscher, Noam	Marvell	Marvell Semiconductor, Inc.	X	X	X
Landry, Gary	Coherent	Coherent Corp.	X	X	X
Law, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise		X	X
Lessard, Stephane	Ericsson AB	Ericsson AB	X	X	X
Lewis, David	SPECIPHY, LUMENTUM	SPECIPHY / Lumentum	X	X	X
Li, jiaqi	Huawei Technologies Co., Ltd				X
Li, Mike-Peng	Intel Corporation	Altera Corporation		X	X
Li, Pei-Rong	MediaTek Inc.	MediaTek Inc.	X	X	X
Li, Yabo	Mediatek Inc	Mediatek Inc	X	X	X
Little, Terrance	Foxconn Electronics Inc.	Foxconn Electronics Inc.	X	X	X
Liu, Cathy	Broadcom Corporation	Broadcom Corporation	X	X	X
Lou, Wei	Broadcom Corporation			X	X
lu, chao	BMW Group	BMW Group		X	
Lusted, Kent	Synopsys, Inc.	Synopsys, Inc.	X	X	X
Lyu, Yunping(Lily)	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X	X	X
Maki, Jeffery	Hewlett Packard Enterprise	Hewlett Packard Enterprise	X	X	X
Maniloff, Eric	Ciena Corporation	Ciena Corporation	X	X	X
Mascitto, Marco	Nokia	Nokia Canada Inc.	X	X	X
Matuz, Balazs	Huawei Technologies Duesseldorf GmbH		X	X	X
Mazzini, Marco	Cisco Systems, Inc.	Cisco Systems, Inc.	X	X	X
Mei, Richard	CommScope, Inc.	CommScope Technologies LLC		X	X

Mellitz, Richard	Samtec, Inc.	Samtec, Inc.	X	X	X
mi, guangcan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X	X	X
Mitcheltree, Tom	US Conec, Ltd.	US Conec, Ltd.	X	X	
Moorwood, Charles	Keysight Technologies	Keysight Technologies	X	X	X
Muller, Shimon	Enfabrica	Enfabrica Corp.	X	X	X
MURAKAMI, YUKI	1Finity	1Finity	X	X	X
Murty, Ramana	Broadcom Corporation	Broadcom Inc.	X	X	X
Muth, Karlheinz	Broadcom Corporation	Broadcom Corporation	X	X	X
Nicholl, Gary	Cisco Systems, Inc.	Cisco Systems, Inc.		X	X
Nicholl, Shawn	Advanced Micro Devices (AMD)	Advanced Micro Devices (AMD)	X	X	X
Noujeim, Leesa	Google	Google	X		
Nowell, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.	X	X	X
Oluwole, Olakanmi	NVIDIA Corporation			X	
Omori, Kumi	NEC Corporation	NEC Corporation	X	X	X
Opsasnick, Eugene	Broadcom Inc.	Broadcom Inc.	X	X	X
Osorio, Luz	Nokia	Nokia Canada Inc.	X	X	X
Pal, Debajyoti	ON Semiconductor				X
Palkert, Thomas	Samtec, Inc.	Samtec, Inc.	X	X	X
Parkholm, Ulf	Ericsson AB	Telefon AB LM Ericsson		X	X
Parthasarathy, Vasu	Broadcom Corporation	Broadcom Corporation		X	X
Perez De Aranda Alonso, Ruben	Cisco Systems, Inc.	Knowledge Development for POF SL	X	X	X
Rabinovich, Rick	Keysight Technologies	Keysight Technologies	X	X	X

Ran, Adee	Cisco Systems, Inc.	Cisco Systems, Inc.	X	X	X
Ransford, Michael	Corning Incorporated		X	X	X
Razavi, Alireza	Eliyan	Eliyan		X	X
Ren, Hao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X	X	X
Rodes, Roberto	II-VI	II-VI	X	X	X
Rysin, Alexander	NVIDIA	NVIDIA	X	X	X
Sakai, Toshiaki	socionext	Socionext Inc.	X	X	X
Sambasivan, Sam	AT&T	AT&T	X	X	
Sedarat, Hossein	Ethernovia	Ethernovia		X	X
Sharon, Ari	Terawand		X	X	X
Shrikhande, Kapil	Upscale AI	Marvell Semiconductor, Inc.	X	X	X
Simms, William	NVIDIA Corporation	NVIDIA Corporation	X	X	X
Sommers, Scott	Molex Incorporated	Molex LLC	X	X	X
Son, Yung Sung	Optomind Inc	Optomind Inc	X	X	X
Sorbara, Massimo	GLOBALFOUNDRIES	GLOBALFOUNDRIES	X	X	X
Srivastava, Atul	NTT Electronics	NEL-America	X	X	X
Sun, Wensheng	Credo Semiconductor	Credo Semiconductor	X	X	X
Swelland, Joseph	Tektronix, Inc.	Tektronix, Inc.	X	X	X
Swenson, Norman	Norman Swenson Consulting; Point2 Technology Inc.; Nokia	Norman Swenson Consulting	X	X	X
TAKAHARA, TOMOO	1FINITY	FUJITSU LABORATORIES LIMITED	X	X	X
Tan, Kan	Tektronix, Inc.	Tektronix, Inc.	X	X	X
Tanc, Ahmet	NXP Semiconductors	NXP Semiconductors		X	X
Tartaglia, Antonio	Ericsson AB	Ericsson AB	X	X	X
Tooyserkani, Pirooz	Cisco Systems, Inc.	Cisco Systems, Inc.	X	X	X

Torres, Luisma	KD	Knowledge Development for POF SL		X	X
Tracy, Nathan	TE Connectivity	TE Connectivity	X	X	X
Tran, Viet	Keysight Technologies	Keysight Technologies	X	X	X
Tu, Mike	Broadcom Corporation	Broadcom Corporation	X		X
Vanderlaan, Paul	Panduit Corp.	Panduit Corp.		X	X
Voss, Robert	Panduit Corp.	Panduit		X	
wan, rongjie	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X	X	X
Wang, Haojie	China Mobile Communications Corporation (CMCC)	China Mobile Communications Corporation (CMCC)			X
Wang, Tongtong	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X	X	X
Wang, Xiaofeng	Qualcomm Incorporated	Qualcomm Incorporated	X	X	X
WANG, Xuebo	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X	X	X
Weaver, James	Arista Networks	Arista Networks	X	X	X
Wei, Terry	Analog Devices Inc.			X	
Welch, Brian	Luxtera	Cisco Systems, Inc.	X	X	X
Wig, Timothy	Samtec, Inc.	Samtec, Inc.	X	X	X
Wingrove, Michael	Ciena Corporation	Ciena Corporation	X	X	X
Withey, James	Fluke Corporation	Fluke Corporation	X	X	X
Wu, Dance	Infineon Technologies	Infineon Technologies			X
Wu, Mau-Lin	MediaTek Inc.	MediaTek Inc.	X	X	X
Xiao, Shiyu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X	X	X
XU, LI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X	X	X
xu, wenxiong	HGGenuine	HG Genuine	X	X	X
Xu, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X	X	X
YANG, Yumeng	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X	X	X

Zhuang, Yan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X	X	X
Zivny, Pavel	Lumilens	Lumilens	X	X	X
Zou, Congshi	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X	X	X